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AMENDMENT UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP 2814
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kouki OGAWA, et al.

Appln. No.: 09/538,469

Confirmation No.: Unassigned

Group Art Unit: 2814

Filed: March 29, 2000

Examiner: N. Ha

For: CAPACITOR-BUILT-IN TYPE PRINTED WIRING SUBSTRATE, PRINTED
WIRING SUBSTRATE, AND CAPACITOR

AMENDMENT UNDER 37 C.F.R. § 1.116

ATTN: **BOX AF**
Commissioner for Patents
Washington, D.C. 20231

Sir:

Responsive to the outstanding final Office Action dated October 19, 2001, please amend
the above-identified application as follows.

IN THE CLAIMS:

Please enter the following amended claims:

1. (Twice Amended) A printed wiring substrate having a planar surface and a built-in
capacitor distinct from the printed wiring substrate on which an IC chip is mounted, said printed
wiring substrate comprising a capacitor accommodation cavity for accommodating the capacitor,
characterized in that: